

Title (en)

Method and apparatus for winding of windable substrates

Title (de)

Verfahren und Vorrichtung zum Aufwickeln von wickelfähigen Substraten

Title (fr)

Procédé et dispositif pour enrouler des substrats enroulables

Publication

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Application

EP 92810166 A 19920304

Priority

EP 92810166 A 19920304

Abstract (en)

[origin: US5374006A] A substrate capable of being wound is transported to a substrate carrier and wound onto the latter. For that purpose the substrate is first held in a defined storage position. With the substrate in that storage position the substrate carrier is moved into a threading position and brought into engagement with the substrate. The substrate is then automatically threaded around the substrate carrier. When the threading operation is complete, the substrate carrier is moved into a winding position in which the substrate is wound onto the substrate carrier. The rate of feed at which the substrate is transported by a motor to the substrate carrier is regulatable. The substrate carrier is motor-driven in a controllable manner, at a uniform torque and in dependence on the feed rate at which the substrate is transported to the substrate carrier. When the winding operation is complete the substrate is cut and the end of the substrate belonging to the winding is automatically fixed to the winding, while the other end of the substrate is again held in the defined storage position.

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